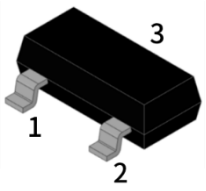
BAV70LDT1

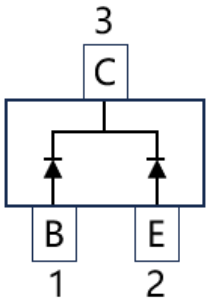
SWITCHING DIODE

1. FEATURES

- The material of product compliance with RoHS requirements and Halogen Free.
- High Stability and High Reliability.
- Extremely Fast Switching Speed



SOT23 (TO-236)



2. Mechanical Data

- SOT-23 Small Outline Plastic Package.
- Tin plated leads, solderable per J-STD-002 and JESD22-B102.
- Marking: A4

3. ORDERING INFORMATION

Device	Min Pack	Inner Box	Outer Carton	Reel
BAV70LDT1	3000	45000	180000	7 inch

4. MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Limit	Unit
DC Blocking Voltage	VR	70	V
Reverse Breakdown Voltage	VRM	70	V
Forward Current	IF	200	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	IFSM	2	A
Repetitive Peak Forward Current	IFRM	500	mA
Power Dissipation	PD	200	mW

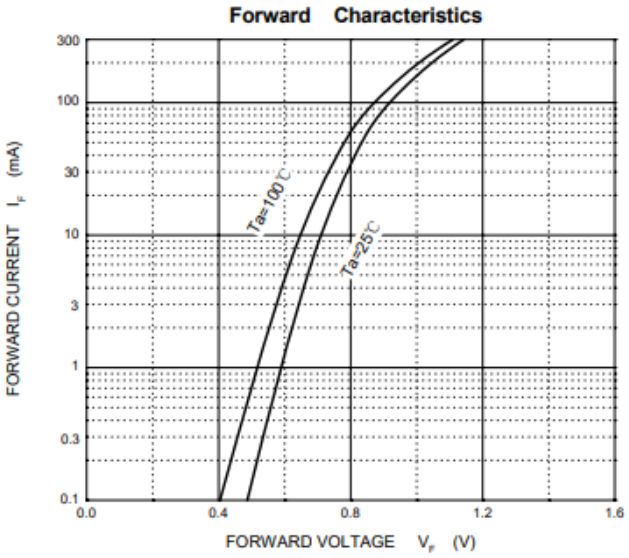
5. THERMAL CHARACTERISTICS

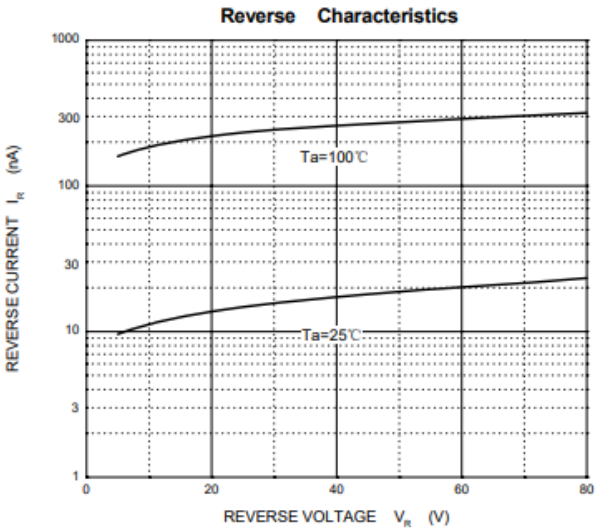
Thermal Resistance Junction to Ambient	RθJA	556	℃/W
Operation Junction and Storage Temperature Range	TJ,TSTG	-55-150	℃

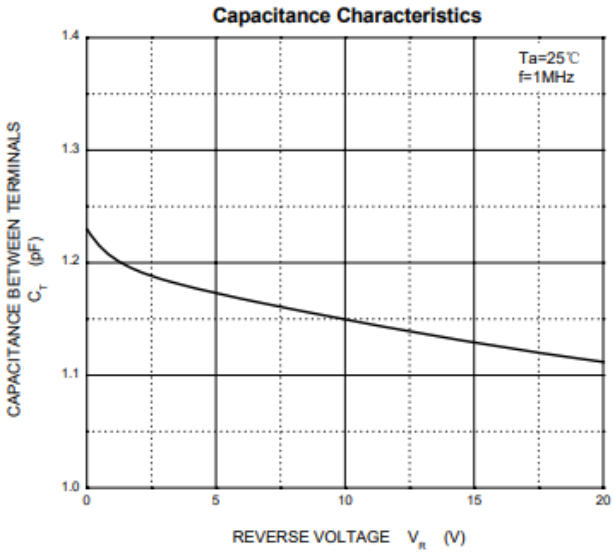
6. ELECTRICAL CHARACTERISTICS (Ta= 25°C unless otherwise specified)

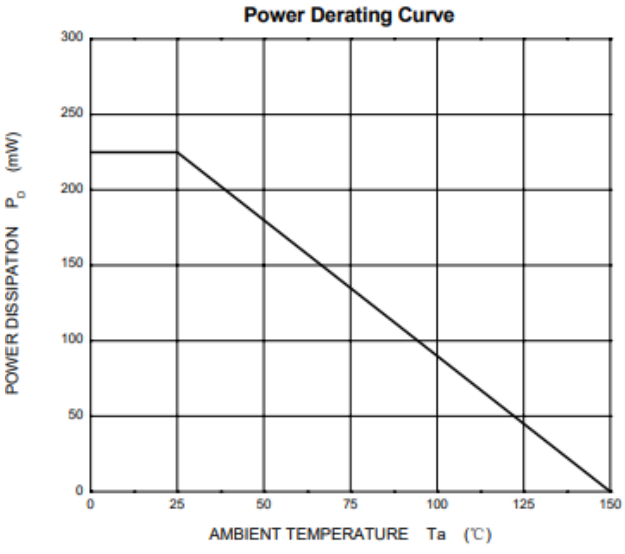
Parameter	Symbol	Condition	Min	Max	Unit
Reverse Breakdown Voltage	V(BR)	IR=0.1mA	70		V
Forward Voltage	VF	IF=0.1mA		0.715	V
		IF=1mA		0.855	V
		IF=10mA		1	V
		IF=30mA		1.25	V
Reverse Voltage Leakage Current	IR	VR=70V		2.5	μA
Capacitance between terminals	CT	VR=0,f=1MHZ		1.5	PF
Reverse recovery time	trr	IF=IR=10mA,RL=100Ω,IRR=0.1IR		6	ns

7.ELECTRICAL CHARACTERISTICS CURVES

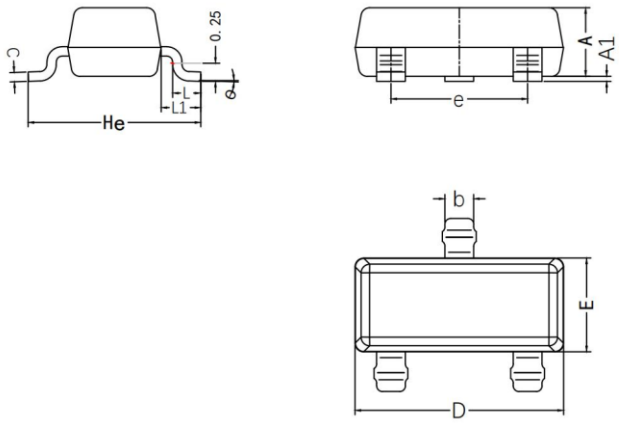






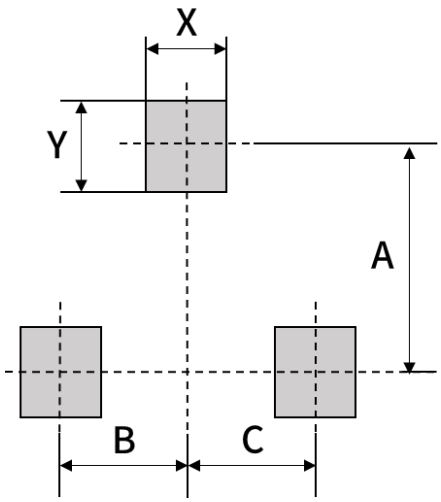


8.OUTLINE AND DIMENSIONS



DIM	MIN	NOR	MAX
A	0.85	0.95	1.05
A1	0.01	0.06	0.10
b	0.36	0.44	0.52
c	0.09	0.13	0.18
D	2.80	2.90	3.10
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.40	0.50
L1	0.35	0.50	0.65
He	2.10	2.35	2.50
θ	0°	-	10°
All Dimensions in mm			

9. SUGGESTED PAD LAYOUT



SOT23		
DIM	mm	inch
A	2.00	0.079
B	0.95	0.037
C	0.95	0.037
X	0.80	0.031
Y	0.90	0.035

10. DISCLAIMER

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